

**TKHR****THOMAS, KAYDEN, HORSTEMEYER & RISLEY, L.L.P.**

ATTORNEYS AT LAW

100 Galleria Pkwy, NW  
Suite 1750  
Atlanta, GA 30339-5948  
www.tkhr.com

Eric Ringer

eric.ringer@tkhr.com

**FACSIMILE TRANSMISSION**

August 13, 2004

[062002-1751]

**TO**

Parvis Hassanzadeh

FAX: 571 273 1435

TEL: 571 272 1435

**FROM**

Eric Ringer

FAX: 770-951-0933

TEL: 770 933 9500

**RE: 09/855,972**

(Message) Examiner Hassanzadeh, this is transmission 4 of 5.

**Number of Pages (Including This Cover Sheet): - 28 - Page(s)**  
**PLEASE ACKNOWLEDGE SAFE AND CLEAR RECEIPT OF ALL PAGES.****CONFIDENTIAL**

The information in this facsimile message is legally privileged and confidential information intended only for the use of the individual or entity named above. If the reader of this message is not the intended recipient, you are hereby notified that any dissemination, distribution or reproduction of this communication is strictly prohibited. If you have received this facsimile in error, please notify us by telephone and return the original message to us at the address above via the United States Postal Service. Thank you.

INTERNATIONAL PATENT, TRADEMARK AND COPYRIGHT LAW AND RELATED LITIGATION

Huntsville, Alabama

Atlanta, Georgia

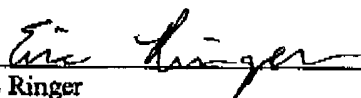
PAGE 1/28 \* RCVD AT 8/13/2004 12:22:37 PM [Eastern Daylight Time] \* SVR:USPTO-EFXXRF-3/24 \* DNIS:2731435 \* CSID: \* DURATION (mm-ss):11-38

**CERTIFICATE OF FACSIMILE**

I hereby certify that this correspondence is being transmitted by facsimile to:

**ATTN: Parvis Hassanzadeh**  
**Facsimile number: 571 273 1435**  
**Commissioner for Patents**  
**P.O. Box 1450**  
**Alexandria, Virginia 22313-1450**

on August 13, 2004.

  
Eric Ringer

In re application of:	<b>Kevin P. Martin et al.</b>	Confirmation No.: <b>1603</b>
U.S. Serial Number:	<b>09/855,972</b>	Art Unit: <b>1763</b>
Filing Date:	<b>May 15, 2001</b>	Examiner: <b>Hassanzadeh, Parvis</b>
Our Reference Number:	<b>62002-1751</b>	

**Title: Method and Apparatus for Low Energy Electron Enhanced Etching or Substrates in an AC or DC Plasma Environment**

**3 Cited References (Articles Only)**